

CPD21-CTLHR10-06 HyperFast Rectifier Die 10 Amp, 600 Volt

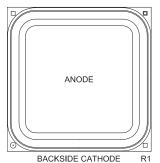
The CPD21-CTLHR10-06 is a silicon HyperFast rectifier designed for motor control and power factor correction applications where extremely fast switching is required.

FEATURES:

• High current

• High voltage

- HyperFast recovery time
- APPLICATIONS:
- Power factor correction
- HYPER FAST
- Motor control



MECHANICAL SPECIFICATIONS:

110 ··· 110 MIL C
110 x 110 MILS
10.2 MILS
Glass
80 x 80 MILS
Al/Ti/Ni/Au – 13,500Å
Al/Ti/Ni/Au – 13,500Å
3.7 MILS
4 INCHES
700

MAXIMUM RATINGS: (T_A=25°C unless otherwise noted)

	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	600	V
DC Blocking Voltage	VR	600	V
RMS Reverse Voltage	V _{R(RMS)}	420	V
Average Forward Current	I _O	10	А
Peak Forward Surge Current, tp=8.3ms	IFSM	150	А
Operating and Storage Junction Temperature	T _{J,} T _{stg}	-65 to +150	°C

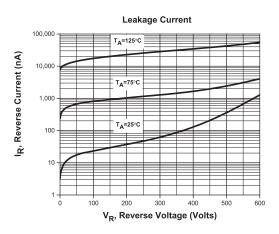
ELECTRICAL CHARACTERISTICS: (T _A =25°C unless otherwise noted)							
SYMBOL	TEST CONDITIONS V _R =600V	MIN	TYP	MAX 10	UNITS		
IR	vR-000v			10	μA		
BVR	I _R =500μA	600			V		
VF	I _F =10A			1.7	V		
VF	I _F =10A, T _A =125°C		1.15		V		
VF	I _F =10A, T _A =-40°C		1.8		V		
СJ	V _R =4.0V, f=1.0MHz		42		pF		
t _{rr}	I _F =10A, V _R =400V, di/dt=200A/µs			25	ns		

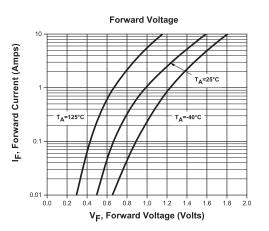
R1 (20-January 2017)

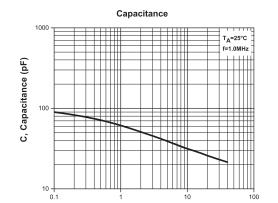
CPD21-CTLHR10-06 Typical Electrical Characteristics



www.centralsemi.com





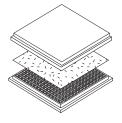


V_R, Reverse Voltage (Volts)

R1 (20-January 2017)

BARE DIE PACKING OPTIONS



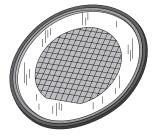


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA Main Tel: (631) 435-1110 Main Fax: (631) 435-1824 Support Team Fax: (631) 435-3388 www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors: www.centralsemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: <u>www.centralsemi.com/terms</u>

